

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



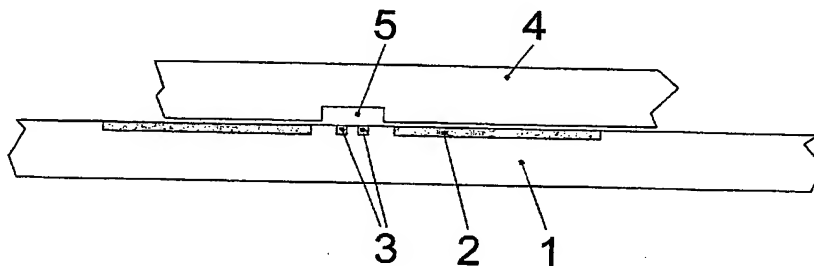
(43) International Publication Date
7 October 2004 (07.10.2004)

PCT

(10) International Publication Number
WO 2004/086529 A1

- (51) International Patent Classification⁷: **H01L 51/20**, 27/15
- (21) International Application Number:
PCT/GB2004/001270
- (22) International Filing Date: 23 March 2004 (23.03.2004)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
0306721.2 24 March 2003 (24.03.2003) GB
- (71) Applicant (for all designated States except US): **MI-CROEMISSIVE DISPLAYS LIMITED** [GB/GB]; Scottish Microelectronics Centre, The King's Buildings, West Mains Road, Edinburgh., EH9 3JF (GB).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **BUCKLEY, Alastair, Robert** [GB/GB]; Flat 2F2, 92 Montpelier Park, Edinburgh., EH10 4NG (GB). **BODAMMER, Georg, Karl, Hermann** [DE/GB]; 8b Gordon Terrace, Edinburgh EH16 5QL (GB). **WHITELEGG, Stephen, Andrew** [GB/GB]; 7 Comiston Court, 121 Comiston Drive, Edinburgh EH10 5QU (GB).
- (74) Agent: **HANSON, William, Bennett**; JY & GW Johnson, Kingsbourne House, 229-231 High Holborn, London WC1V 7DP (GB).
- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).
- Published:**
- with international search report
 - before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments
- For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD OF FORMING A SEMICONDUCTOR DEVICE



(57) Abstract: A method of forming a semiconductor device from a semiconductor substrate (1) comprising circuitry (2) and terminal means (3) for establishing electrical connection to the circuitry; and a sheet (4) for forming a further layer of the device, the sheet comprising at least one groove (5). Adhesive is applied to at least one of the substrate (1) and the sheet (4); the substrate and the sheet are then aligned in a position such that the groove (5) faces the terminal means (3); and the substrate and the sheet are then attached together by means of the adhesive.